

**Letter of Volatility for Teamconnect Ceiling M (TCC M)**

Sennheiser electronic GmbH & Co. KG understands the importance of security and data protection for our devices when they are applied in sensitive areas. In support of this, Sennheiser makes the following declarations concerning the memory technologies used in these products.

- None of the devices of this LoV stores digital audio data after power off or reboot
- None of the devices of this LoV has non-volatile memory in audio data path. All temporary stored audio data for processing is located in volatile memory only which is not accessible by the user in normal operation.
- additionally see Audinate's LoV for the used Brooklyn 3 Module

Type and size of	eMMC NAND Flash 8 GByte
Usage	Operating system and persistent user configuration
Volatility	Non-volatile
Location	On mainboard
Removable	No. Permanently soldered to mainboard
Process of clearing	Factory reset clears all user configuration data
User modifiable	Persistent user settings can be modified
General Use	Not available for general use in normal operating modes

Type and size of	64-Kbit I²C Serial EEPROM
Usage	Production data
Volatility	Non-volatile
Location	One piece on mic-board (3 boards per Unit)
Removable	No. Permanently soldered to mainboard
Process of clearing	Clearing this memory is not possible
User modifiable	No
General Use	Not available for general use

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Type and size of	128M-BIT Serial SPI Flash
Usage	Bootloader
Volatility	Non-volatile
Location	On mainboard
Removable	No. Permanently soldered to mainboard
Process of clearing	Clearing this memory is not possible
User modifiable	No
General Use	Not available for general use

Type and size of	DDR3 2GBIT 128M x 16
Usage	System RAM, OS and Audio Buffers
Volatility	Volatile
Location	Two pieces on mainboard
Removable	No. Permanently soldered to mainboard
Process of clearing	Cleared upon power-down, non-recoverable
User modifiable	No
General Use	Not available for general use

Type and size of	640KB L1 SRAM
Usage	ADSP-SC589 internal RAM
Volatility	Volatile
Location	Integral component of SoC located on the mainboard
Removable	No, integral component of the SoC
Process of clearing	Cleared upon power-down, non-recoverable
User modifiable	No
General Use	Not available for general use

Type and size of	256KB L2 SRAM
Usage	ADSP-SC589 internal RAM
Volatility	Volatile
Location	Integral component of SoC for every core located on mainboard
Removable	No, integral component of the SoC
Process of clearing	Cleared upon power-down, non-recoverable
User modifiable	No
General Use	Not available for general use



Type and size of	32KB L1 SRAM
Usage	ARM core data cache at ADSP-SC589
Volatility	Volatile
Location	Integral component of SoC (Mainboard)
Removable	No, integral component of the SoC
Process of clearing	Cleared upon power-down, non-recoverable
User modifiable	No
General Use	Not available for general use

Type and size of	256KB L2 SRAM
Usage	ARM core data cache at ADSP-SC589
Volatility	Volatile
Location	Integral component of SoC (Mainboard)
Removable	No, integral component of the SoC
Process of clearing	Cleared upon power-down, non-recoverable
User modifiable	No
General Use	Not available for general use